

## N-Channel 40 V (D-S) Super Junction Power MOSFET



RoHS  
COMPLIANT

| PRODUCT SUMMARY     |                                 |                                   |                       |
|---------------------|---------------------------------|-----------------------------------|-----------------------|
| V <sub>DS</sub> (V) | R <sub>DS(on)</sub> (mΩ) (TYP.) | I <sub>D</sub> (A) <sup>a,d</sup> | Q <sub>g</sub> (TYP.) |
| 40                  | 0.85 at V <sub>GS</sub> = 10 V  | 255                               | 97 nC                 |

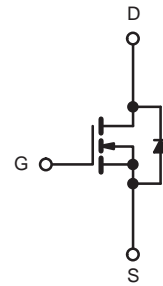
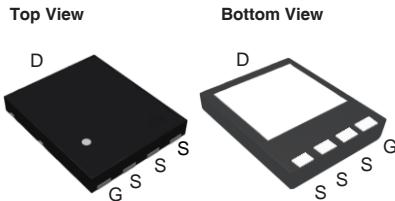
### FEATURES

- DT-SJ Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested
- Excellent Gate Charge x RDS(ON) Product (FOM)

### APPLICATIONS

- Power Management
- Motor Drivers
- DC-DC Converters

### DFN8X8 Pin Configuration



N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C, unless otherwise noted) |                                   |              |      |
|---|-----------------------------------|--------------|------|
| Parameter   | Symbol                            | Limit        | Unit |
| Drain-Source Voltage  | V <sub>DS</sub>                   | 40           | V    |
| Gate-Source Voltage   | V <sub>GS</sub>                   | ± 20         |      |
| Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>           | T <sub>C</sub> = 25 °C            | 255          | A    |
|   | T <sub>C</sub> = 100 °C           | 171          |      |
| Pulsed Drain Current <sup>b</sup>   | I <sub>DM</sub>                   | 900          |      |
| Single Pulse Avalanche Energy   | E <sub>AS</sub>                   | 802          | mJ   |
| Maximum Power Dissipation <sup>c</sup>                                    | T <sub>C</sub> = 25 °C            | 345          | W    |
|   | T <sub>C</sub> = 100 °C           | 125          |      |
| Operating Junction and Storage Temperature Range                          | T <sub>J</sub> , T <sub>stg</sub> | - 55 to +150 | °C   |
| Soldering Recommendations (Peak Temperature)                              |                                   | 260          |      |

| THERMAL RESISTANCE RATINGS               |              |                   |         |         |      |
|--|--------------|-------------------|---------|---------|------|
| Parameter                                |              | Symbol            | Typical | Maximum | Unit |
| Maximum Junction-to-Ambient <sup>d</sup> | t ≤ 10 s     | R <sub>thJA</sub> | -       | 32      | °C/W |
| Maximum Junction-to-Case (Drain)         | Steady State | R <sub>thJC</sub> | -       | 0.36    |      |

### Notes

- Calculated continuous current based on maximum allowable junction temperature.
- Repetitive rating; pulse width limited by max. junction temperature.
- P<sub>d</sub> is based on max. junction temperature, using junction-case thermal resistance.
- The value of R<sub>thJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25 °C.

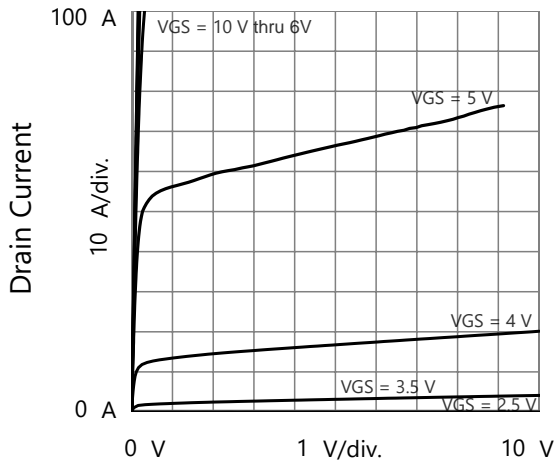
| SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted)                                 |                     |  |      |      |       |      |
|---|---------------------|--|------|------|-------|------|
| PARAMETER   | SYMBOL              | TEST CONDITIONS  | MIN. | TYP. | MAX.  | UNIT |
| <b>Static</b>   |                     |  |      |      |       |      |
| Drain-Source Breakdown Voltage  | V <sub>DS</sub>     | V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA   | 40   | -    | -     | V    |
| Gate Threshold Voltage  | V <sub>GS(th)</sub> | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA  | 2    | -    | 4     |      |
| Gate-Body Leakage   | I <sub>GSS</sub>    | V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 20 V  | -    | -    | ± 100 | nA   |
| Zero Gate Voltage Drain Current   | I <sub>DSS</sub>    | V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V  | -    | -    | 1     | μA   |
|   |                     | V <sub>DS</sub> = 36 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 85 °C  | -    | -    | 10    |      |
| On-State Drain Current <sup>a</sup>   | I <sub>D(on)</sub>  | V <sub>DS</sub> ≥ 10 V, V <sub>GS</sub> = 10 V   | 255  | -    | -     | A    |
| Drain-Source On-State Resistance <sup>a</sup>   | R <sub>DS(on)</sub> | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A  | -    | 0.85 | 1.05  | mΩ   |
| Forward Transconductance <sup>a</sup>   | g <sub>fs</sub>     | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A  | -    | 85   | -     | S    |
| <b>Dynamic <sup>b</sup></b>   |                     |  |      |      |       |      |
| Input Capacitance   | C <sub>ISS</sub>    | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 20 V, f = 1 MHz   | -    | 6890 | -     | pF   |
| Output Capacitance  | C <sub>OSS</sub>    |  | -    | 2015 | -     |      |
| Reverse Transfer Capacitance  | C <sub>RSS</sub>    |  | -    | 277  | -     |      |
| Total Gate Charge <sup>c</sup>  | Q <sub>g</sub>      | V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A  | -    | 97   | -     | nC   |
| Gate-Source Charge <sup>c</sup>   | Q <sub>gs</sub>     |  | -    | 20   | -     |      |
| Gate-Drain Charge <sup>c</sup>  | Q <sub>gd</sub>     |  | -    | 12   | -     |      |
| Gate Resistance   | R <sub>g</sub>      | f = 1 MHz  | -    | 2    | -     | Ω    |
| Turn-On Delay Time <sup>c</sup>   | t <sub>d(on)</sub>  | V <sub>DD</sub> = 20 V, R <sub>L</sub> = 2 Ω<br>I <sub>D</sub> = 30 A, V <sub>GEN</sub> = 10 V, R <sub>g</sub> = 3 Ω | -    | 16   | -     | ns   |
| Rise Time <sup>c</sup>  | t <sub>r</sub>      |  | -    | 11   | -     |      |
| Turn-Off Delay Time <sup>c</sup>  | t <sub>d(off)</sub> |  | -    | 57   | -     |      |
| Fall Time <sup>c</sup>  | t <sub>f</sub>      |  | -    | 10   | -     |      |
| <b>Drain-Source Body Diode Ratings and Characteristics <sup>b</sup> (T<sub>C</sub> = 25 °C)</b> |                     |  |      |      |       |      |
| Continuous Source Current   | I <sub>S</sub>      | T <sub>C</sub> = 25 °C   | -    | -    | 255   | A    |
| Pulsed Source Current   | I <sub>SM</sub>     |  | -    | -    | 900   | A    |
| Forward Voltage <sup>a</sup>  | V <sub>SD</sub>     | I <sub>F</sub> = 1 A, V <sub>GS</sub> = 0 V  | -    | -    | 1.2   | V    |
| Reverse Recovery Time   | t <sub>rr</sub>     | I <sub>F</sub> = 30 A, di/dt = 100 A/μs  | -    | 40   | -     | ns   |
| Reverse Recovery Charge   | Q <sub>rr</sub>     |  | -    | 120  | -     | nC   |

**Notes**

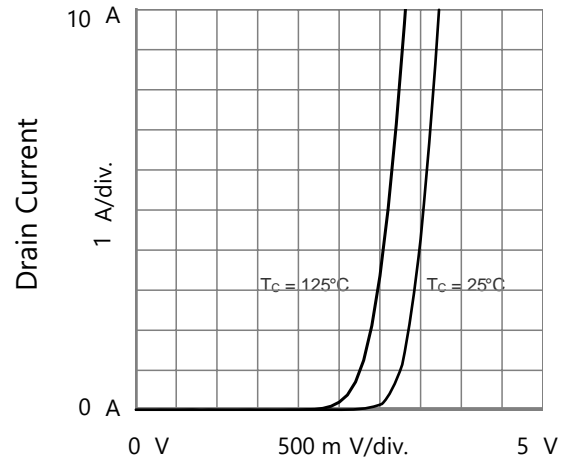
- Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %.
- Guaranteed by design, not subject to production testing.
- Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

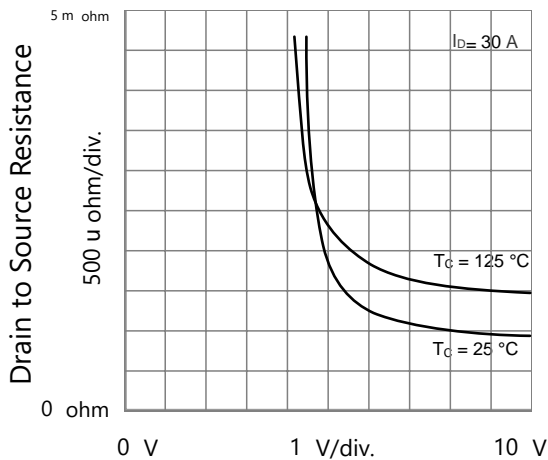
**TYPICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)



Drain to Source Voltage  
Output Characteristics

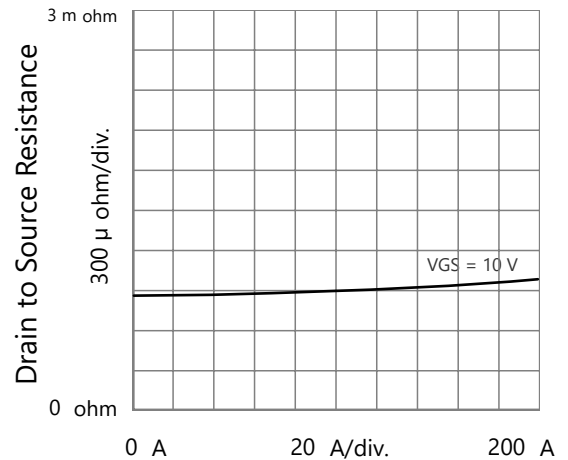


Gate to Source Voltage  
Transfer Characteristics



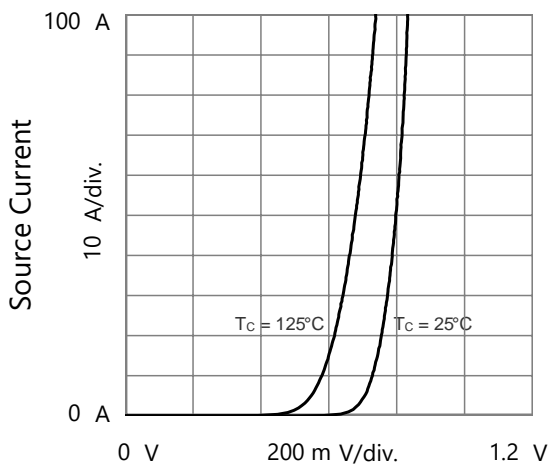
Gate to Source Voltage

Drain to Source Resistance vs. Gate to Source Voltage

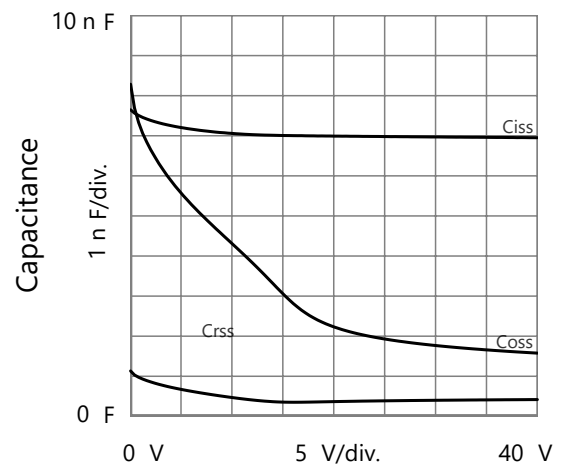


Drain Current

Drain to Source Resistance vs. Drain Current

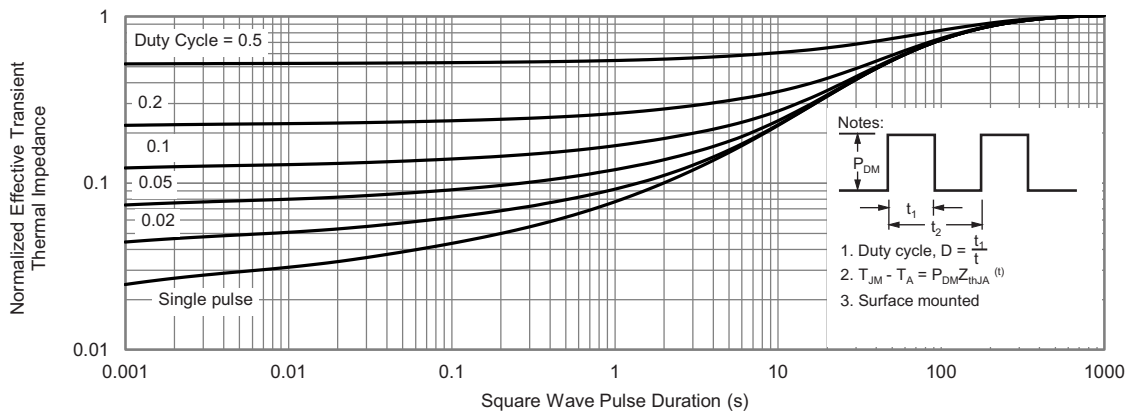
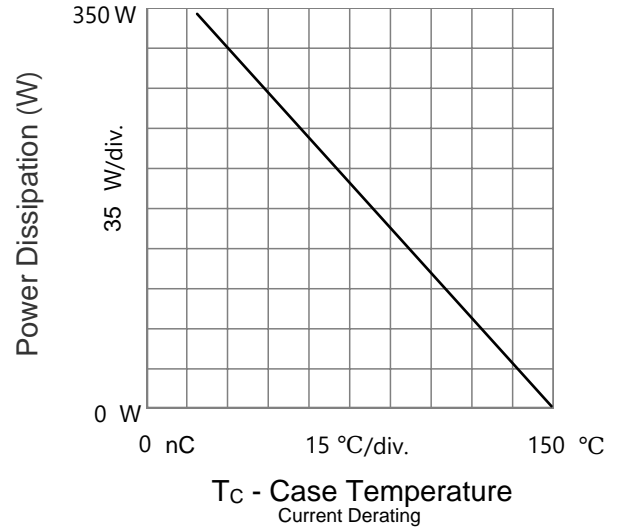
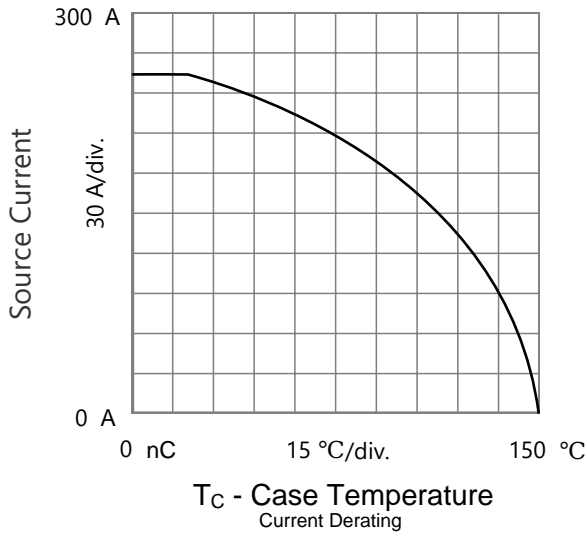
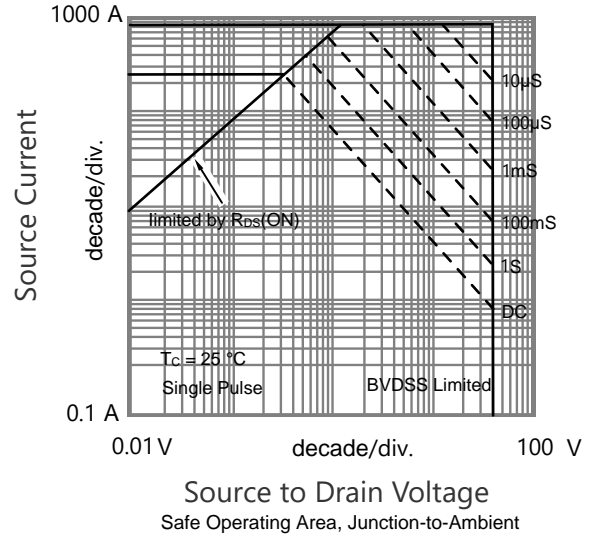
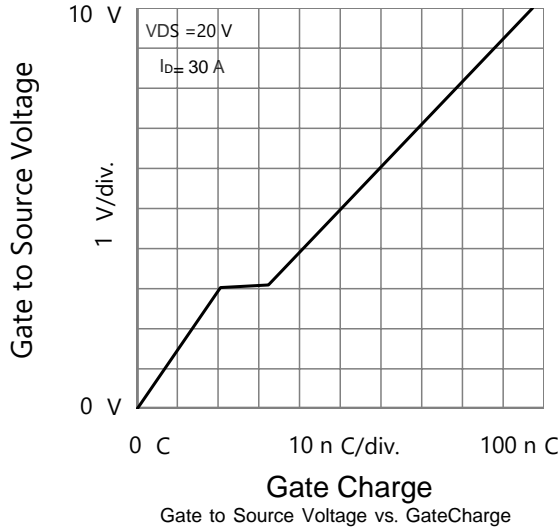


Source to Drain Voltage  
Body Diode Forward Characteristics



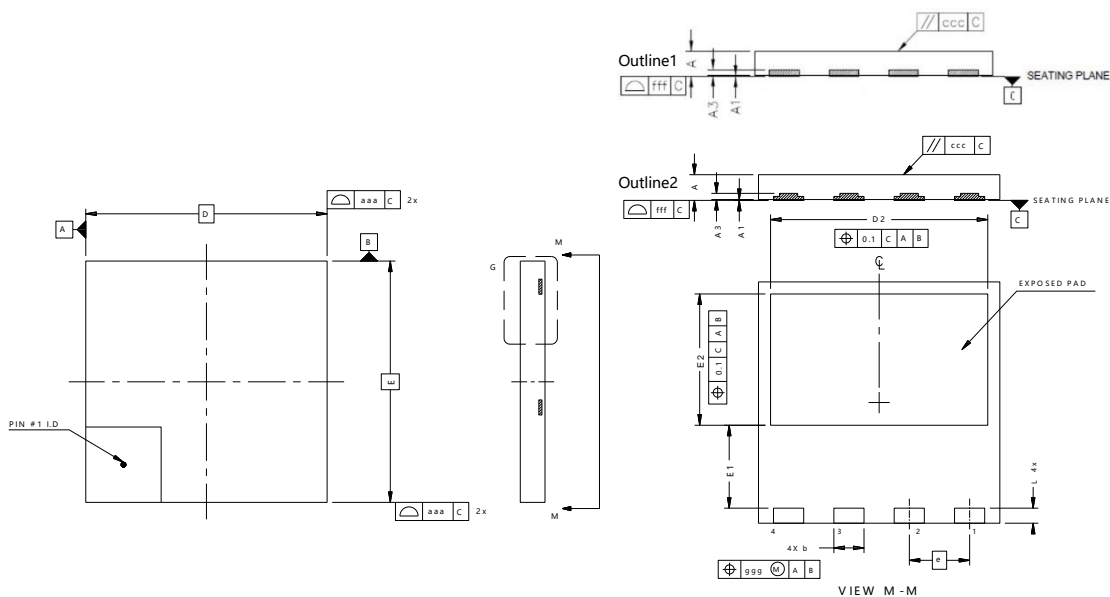
Drain to Source Voltage  
Capacitances

**TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



**Normalized Thermal Transient Impedance, Junction-to-Ambient**

## DFN8\*8 PACKAGE OUTLINE



| Symbol | mm      |      |
|--------|---------|------|
|        | Min     | Max  |
| A      | 0.75    | 1.15 |
| A1     | 0.00    | 0.05 |
| A3     | 0.10    | 0.30 |
| b      | 0.90    | 1.10 |
| D      | 7.85    | 8.15 |
| E      | 7.85    | 8.15 |
| D2     | 7.10    | 7.30 |
| E1     | 2.65    | 2.85 |
| E2     | 4.25    | 4.45 |
| e      | 2.0 BSC |      |
| L      | 0.40    | 0.60 |
| aaa    | 0.1     |      |
| ggg    | 0.05    |      |
| ccc    | 0.05    |      |
| fff    | 0.05    |      |

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